ABSTRACT OF THE DISCLOSURE

An interposer including a fence that receives and aligns a semiconductor device, such as a flip-chip type semiconductor device, with an interposer substrate. The fence may include edges that are configured to progressively align a semiconductor device with the interposer substrate. The fence may also include one or more laterally recessed regions to facilitate rough alignment of a semiconductor device with the interposer substrate. Methods for fabricating the fence include the use of stereolithographic and molding processes. When stereolithography is used to fabricate the fence, a machine vision system that includes at least one camera operably associated with a computer may be used to control a stereolithography apparatus and facilitates recognition of the position and orientation of interposer substrates on and around which material is to be applied in one or more layers to form the fence. As a result, the interposer substrates need not be precisely mechanically aligned.

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